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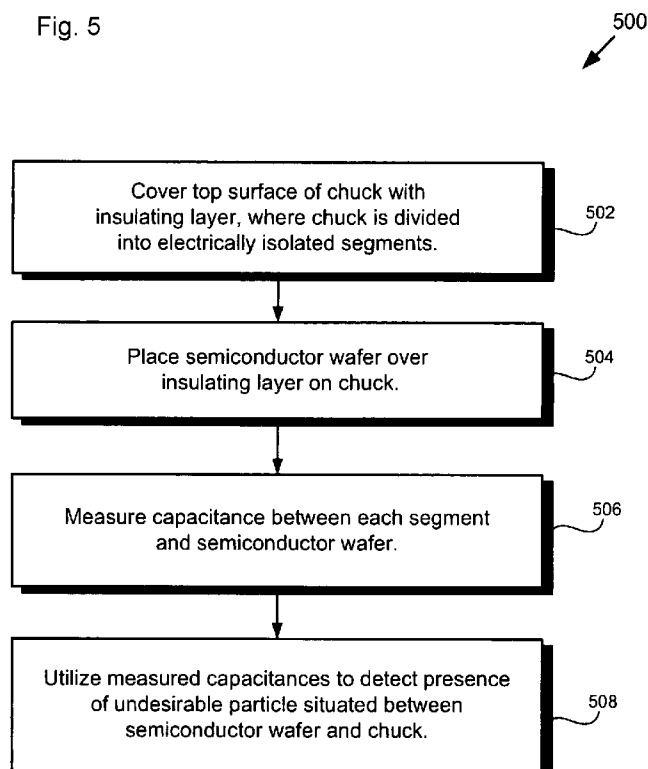
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(54) Title: METHOD AND SYSTEM FOR DETECTING EXISTENCE OF AN UNDESIRABLE PARTICLE DURING SEMI-CONDUCTOR FABRICATION

Fig. 5



(57) Abstract: One exemplary embodiment is a method (500) for detecting existence of an undesirable particle (122) between a planar lithographic object, such as a semiconductor wafer (102) or a lithographic mask (202), and a chuck (104) during semiconductor fabrication. The exemplary method in this embodiment includes placing (504) the planar lithographic object, such as the semiconductor wafer (102), over the chuck. The method further includes measuring a change in at least one electrical characteristic formed by and between the chuck and the planar lithographic object, such as measuring (506) a change in capacitance between the chuck (104) and semiconductor wafer (102), caused by the undesirable particle.



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